

- **Ideal for European 433.92 MHz Transmitters**
- **Very Low Series Resistance**
- **Quartz Stability**
- **Surface-Mount Ceramic Case**
- **Passivation for Enhanced Reliability**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Tape and Reel Standard per ANSI/EIA-481**
- **Moisture Sensitivity Level: 1**
- **AEC-Q200 Qualified**

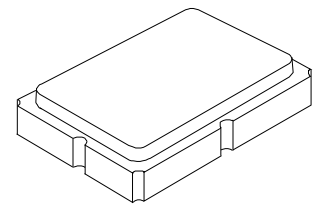
The RO3101A-20 is a true one-port, surface-acoustic-wave (SAW) resonator in a surface-mount, ceramic case. It provides reliable, fundamental-mode, quartz frequency stabilization of fixed-frequency transmitters operating at 433.92 MHz. This SAW is designed specifically for remote-control and wireless security transmitters operating in Europe under ETSI I-ETS 300 220 and in Germany under FTZ 17 TR 2100.

#### Absolute Maximum Ratings

| Rating                                                 | Value      | Units |
|--------------------------------------------------------|------------|-------|
| CW RF Power Dissipation (See: Typical Test Circuit)    | +0         | dBm   |
| DC voltage Between Terminals (Observe ESD Precautions) | ±30        | VDC   |
| Case Temperature                                       | -40 to +85 | °C    |
| Soldering Temperature (10 seconds / 5 cycles max.)     | 260        | °C    |

**RO3101A-20**

**433.92 MHz  
SAW Resonator**



**SM5035-4**

| Characteristic                                      | Sym                                  | Notes        | Minimum    | Typical | Maximum | Units               |
|-----------------------------------------------------|--------------------------------------|--------------|------------|---------|---------|---------------------|
| Center Frequency (+25 °C)                           | Absolute Frequency                   | $f_C$        | 433.845    |         | 433.995 | MHz                 |
|                                                     | Tolerance from 433.920 MHz           | $\Delta f_C$ |            |         | ±75     | kHz                 |
| Insertion Loss                                      | IL                                   |              |            | 1.5     | 2.2     | dB                  |
| Quality Factor                                      | Unloaded Q                           | $Q_U$        |            | 9000    |         |                     |
|                                                     | 50 $\Omega$ Loaded Q                 | $Q_L$        |            | 1458    |         |                     |
| Temperature Stability                               | Turnover Temperature                 | $T_O$        | 10         | 25      | 40      | °C                  |
|                                                     | Turnover Frequency                   | $f_O$        |            | $f_C$   |         |                     |
|                                                     | Frequency Temperature Coefficient    | FTC          |            | 0.032   |         | ppm/°C <sup>2</sup> |
| Frequency Aging                                     | Absolute Value during the First Year | $ f_A $      |            | ≤10     |         | ppm/yr              |
| DC Insulation Resistance between Any Two Terminals  |                                      |              | 1.0        |         |         | M $\Omega$          |
| RF Equivalent RLC Model                             | Motional Resistance                  | $R_M$        |            | 19.4    |         | $\Omega$            |
|                                                     | Motional Inductance                  | $L_M$        |            | 63.8    |         | $\mu$ H             |
|                                                     | Motional Capacitance                 | $C_M$        |            | 2.11    |         | fF                  |
|                                                     | Shunt Static Capacitance             | $C_O$        |            | 2.4     |         | pF                  |
| Test Fixture Shunt Inductance                       |                                      | $L_{TEST}$   |            | 55.1    |         | nH                  |
| Lid Symbolization (YY = Year, WW = Week, S = Shift) |                                      |              | 778, YYWWS |         |         |                     |



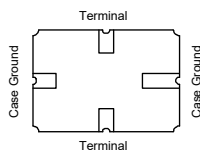
**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

#### NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

## Electrical Connections

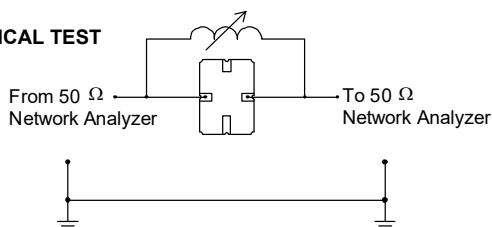
The SAW resonator is bidirectional and may be installed with either orientation. The two terminals are interchangeable and unnumbered. The callout NC indicates no internal connection. The NC pads assist with mechanical positioning and stability. External grounding of the NC pads is recommended to help reduce parasitic capacitance in the circuit.



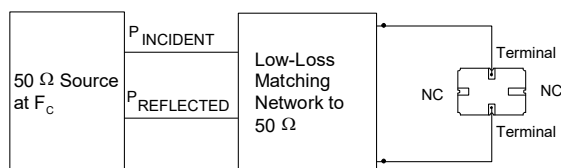
## Typical Test Circuit

The test circuit inductor,  $L_{TEST}$ , is tuned to resonate with the static capacitance,  $C_O$ , at  $F_C$ .

### ELECTRICAL TEST



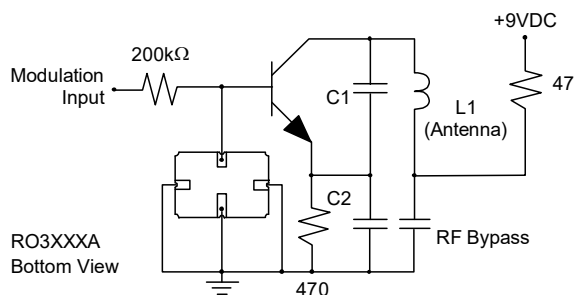
### POWER TEST



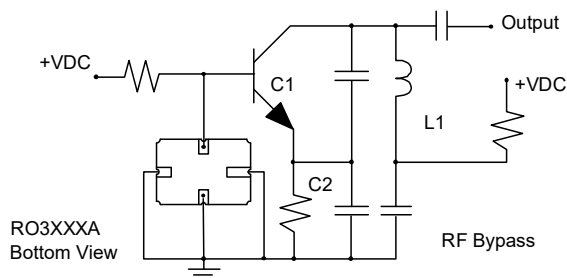
$$CW \text{ RF Power Dissipation} = P_{INCIDENT} - P_{REFLECTED}$$

## Typical Application Circuits

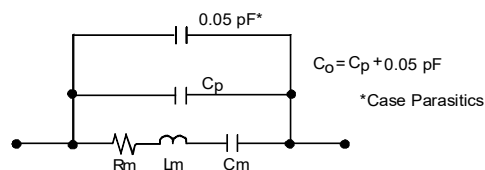
### Typical Low-Power Transmitter Application



### Typical Local Oscillator Applications

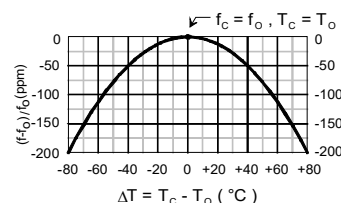


### Equivalent LC Model



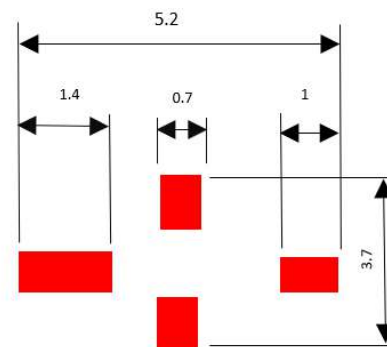
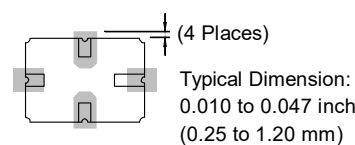
### Temperature Characteristics

The curve shown on the right accounts for resonator contribution only and does not include LC component temperature contributions.



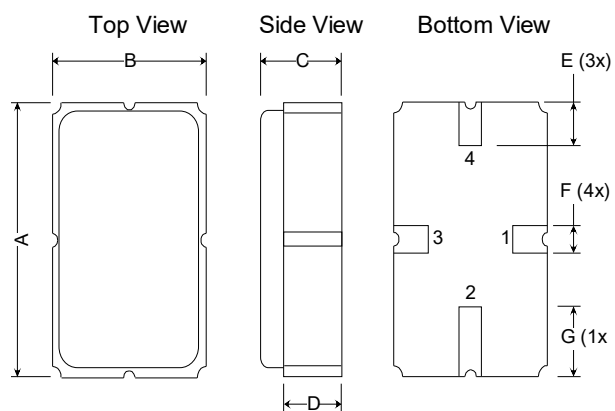
### Typical Circuit Board Land Pattern

The circuit board land pattern shown below is one possible design. The optimum land pattern is dependent on the circuit board assembly process which varies by manufacturer. The distance between adjacent land edges should be at a maximum to minimize parasitic capacitance. Trace lengths from terminal lands to other components should be short and wide to minimize parasitic series inductances.



PCB Footprint

## Case Design



| Dimensions | Millimeters |      |      | Inches |       |       |
|------------|-------------|------|------|--------|-------|-------|
|            | Min         | Nom  | Max  | Min    | Nom   | Max   |
| A          | 4.87        | 5.00 | 5.13 | 0.191  | 0.196 | 0.201 |
| B          | 3.37        | 3.50 | 3.63 | 0.132  | 0.137 | 0.142 |
| C          | 1.45        | 1.53 | 1.60 | 0.057  | 0.060 | 0.062 |
| D          | 1.35        | 1.43 | 1.50 | 0.040  | 0.057 | 0.059 |
| E          | 0.67        | 0.80 | 0.93 | 0.026  | 0.031 | 0.036 |
| F          | 0.37        | 0.50 | 0.63 | 0.014  | 0.019 | 0.024 |
| G          | 1.07        | 1.20 | 1.33 | 0.042  | 0.047 | 0.052 |

## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

